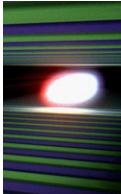




The European XFEL deformable optics project

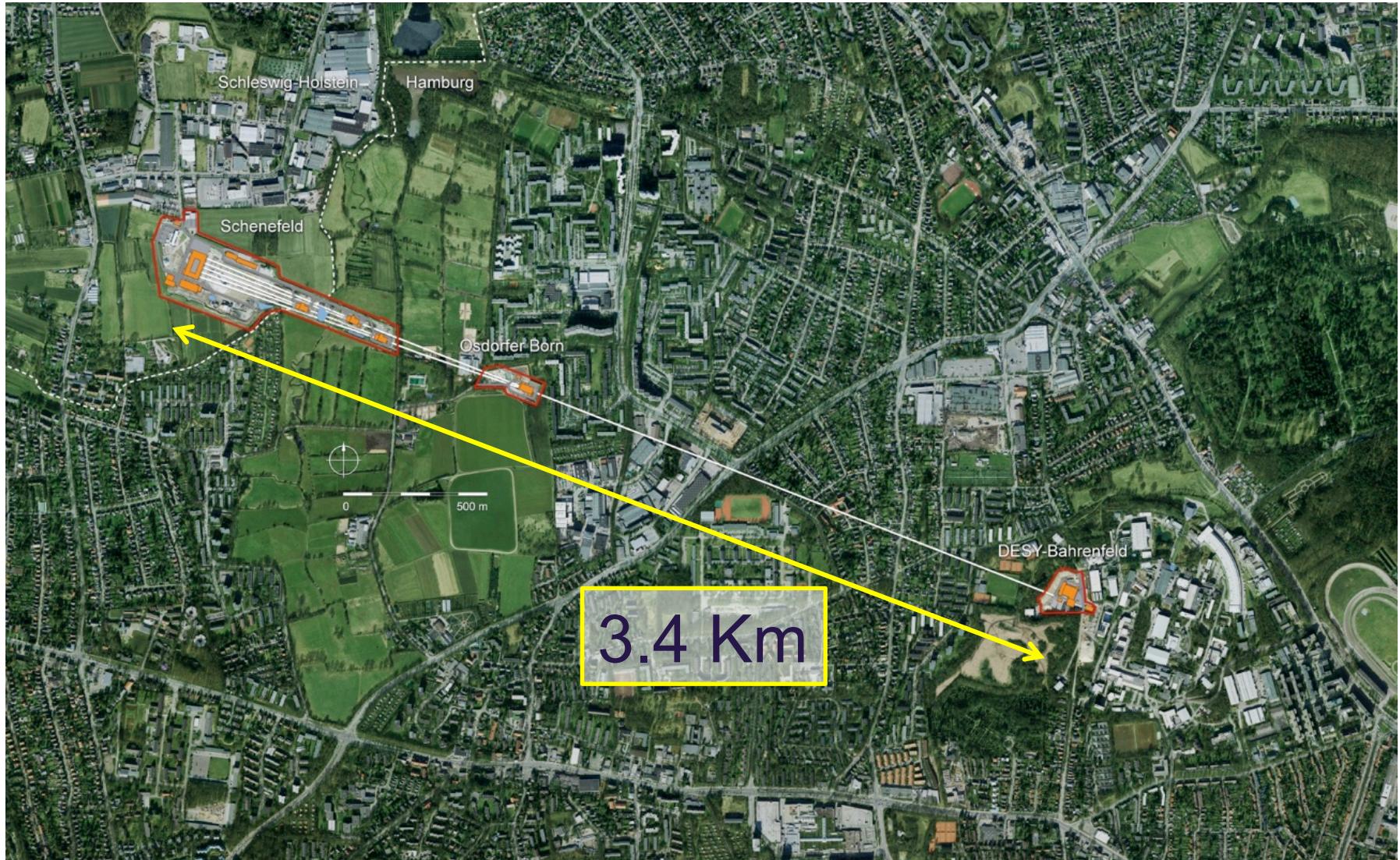
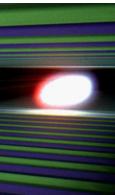
Maurizio Vannoni
(European XFEL GmbH)



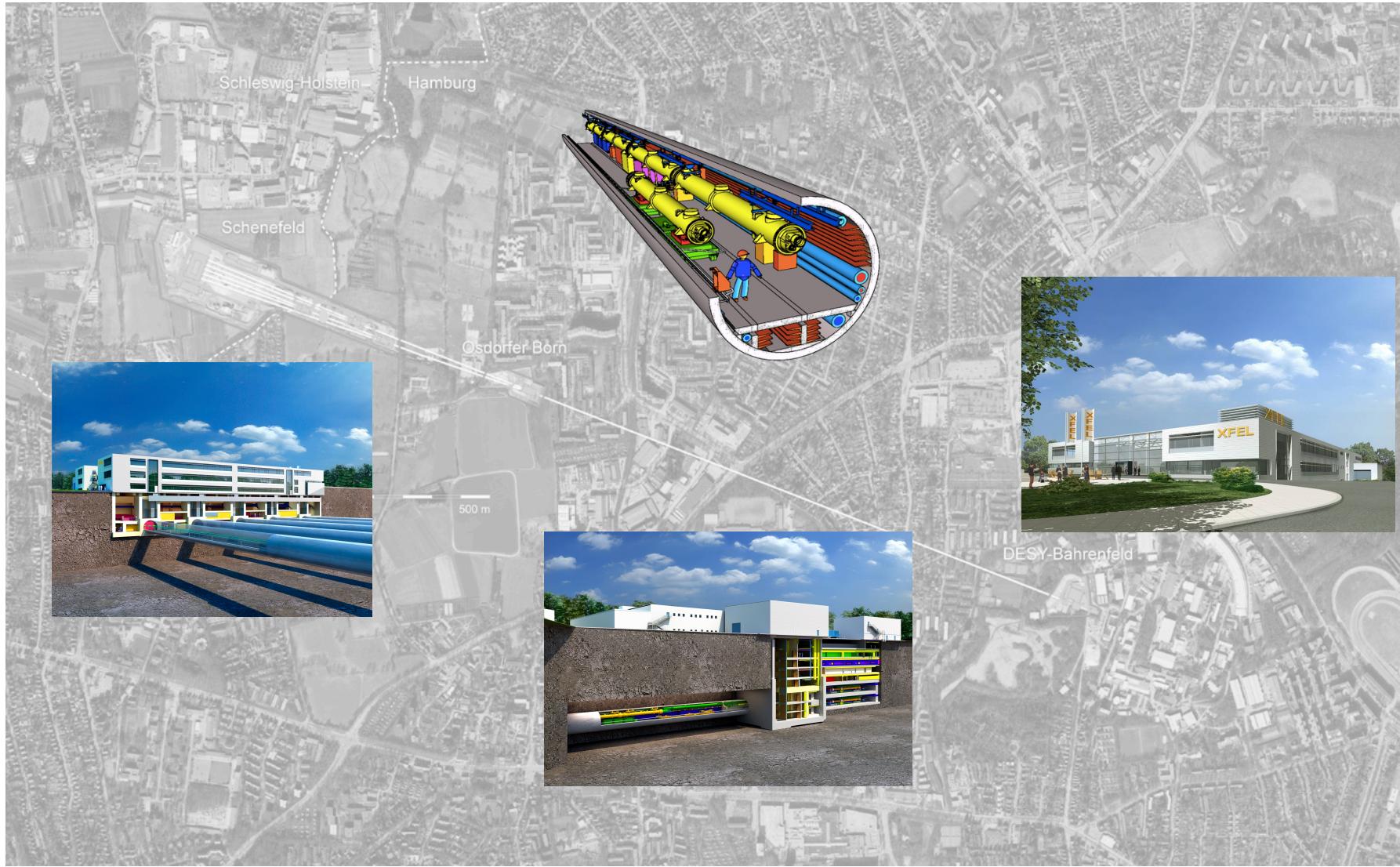
Contents

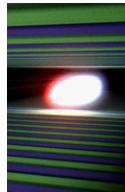
- Overview of the European XFEL project
- Bendable Mirrors in the Distribution System
- General Specifications
- Metrology
- Status of the project and future plans

Overview of the European XFEL project



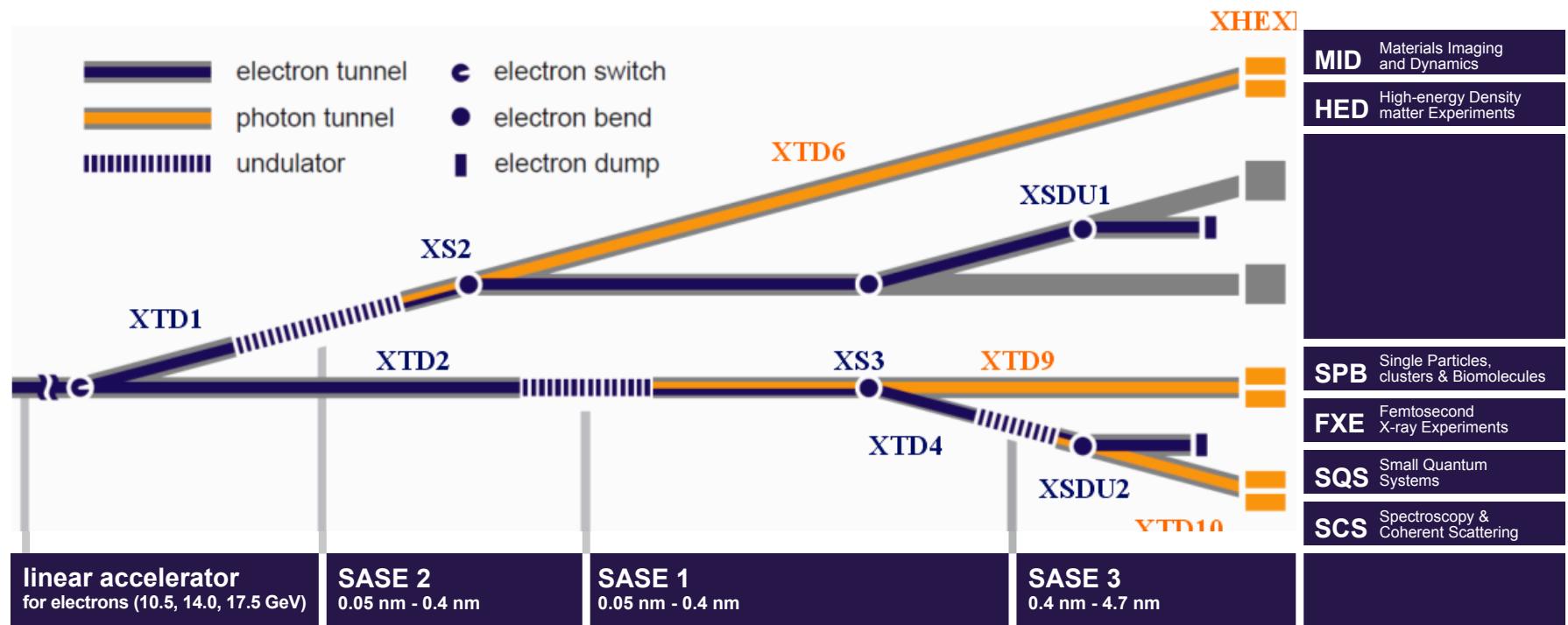
Overview of the European XFEL project

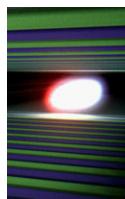




Overview of the European XFEL project

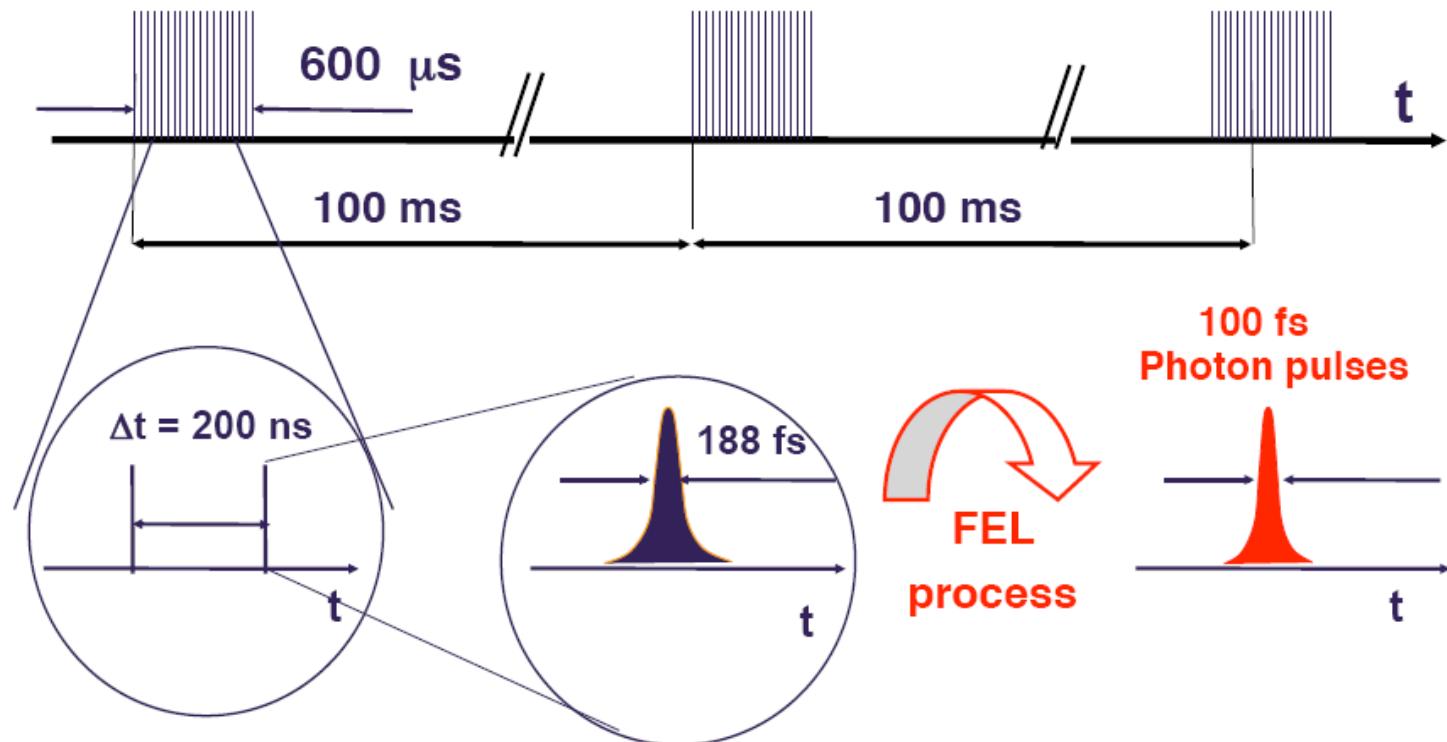
Undulator Segment	FEL radiation energy [keV]	Wavelength [nm]
SASE 1	3 - over 24	0.4 - 0.05
SASE 2	3 - over 24	0.4 - 0.05
SASE 3	0.27 - 3	4.7 – 0.4

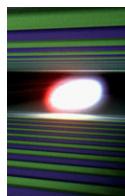




Overview of the European XFEL project

Up to 27000 pulses every second
(2700 pulses / 10 Hz)





Thermal effect on offset mirror

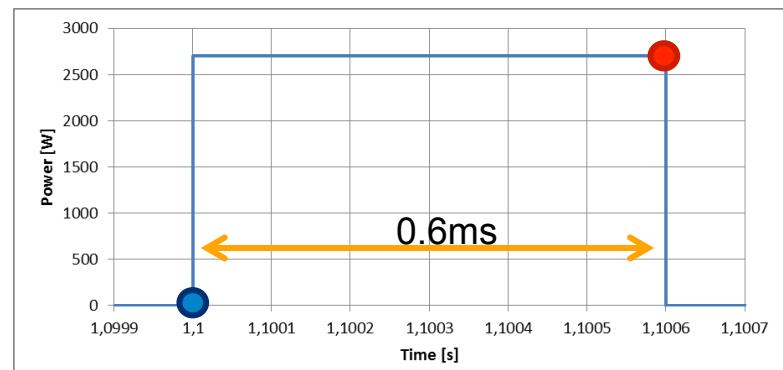
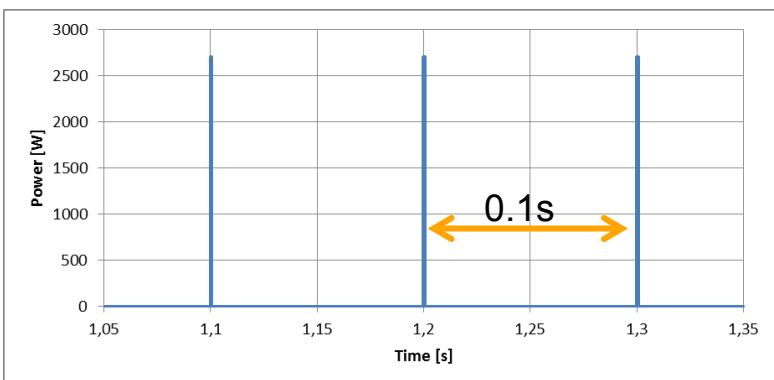
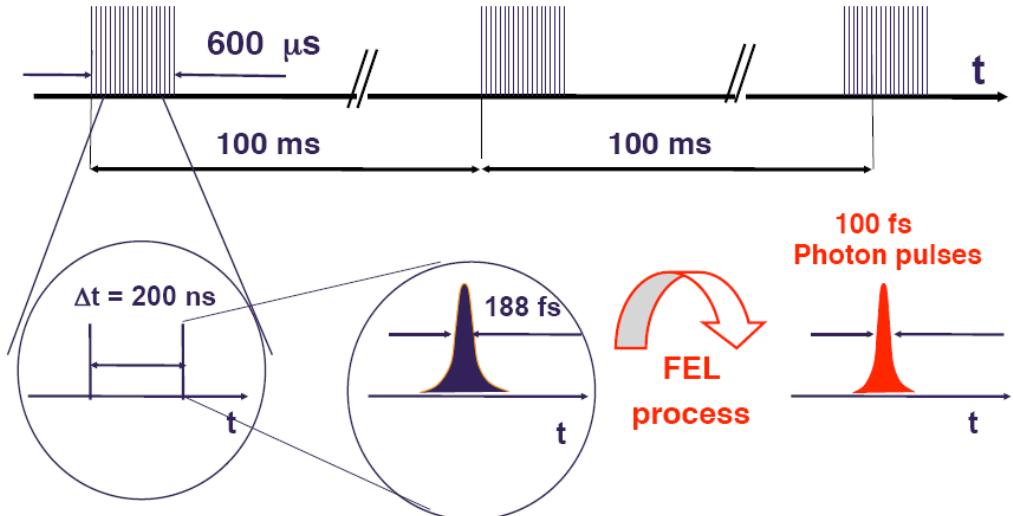
M. Altarelli et al., *The XFEL Technical Design Report*, 2006

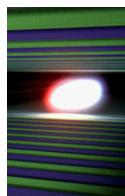
Pulse time structure:

- # pulses / train = 2700
- Pulse train duration = 0,6ms
- Pulse train rep. rate = 10Hz

Assuming 10mJ as pulse energy:

- P_{pulse} = 100GW
- P_{train} = 45kW
- P = 270W

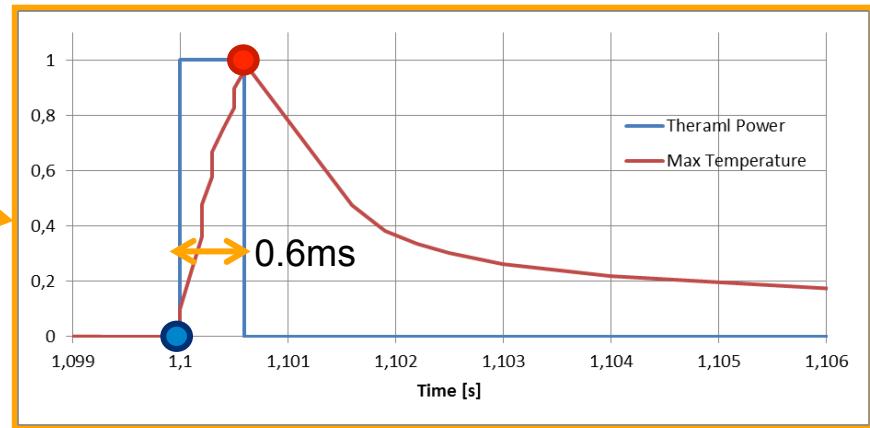
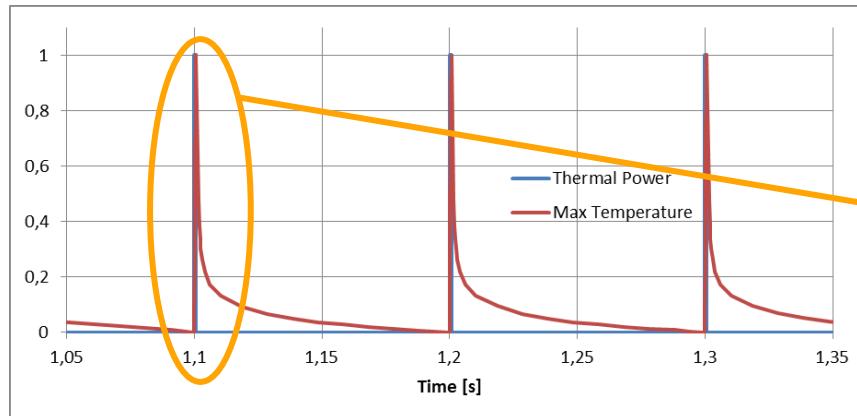




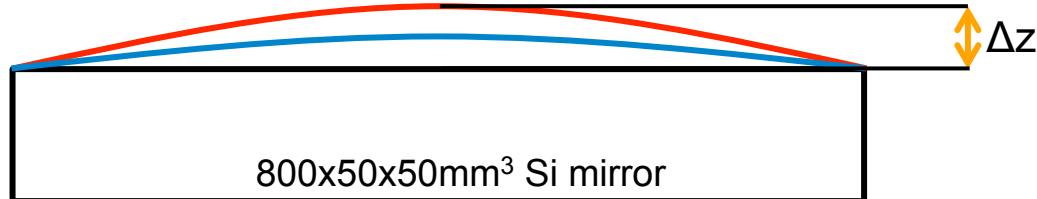
Thermal effect on offset mirror

(Simulations by Daniele La Civita and Antje Trapp)

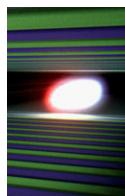
Max temperature variation ($\Delta T_{\max} = 0.3\text{-}0.6^\circ\text{C}$)



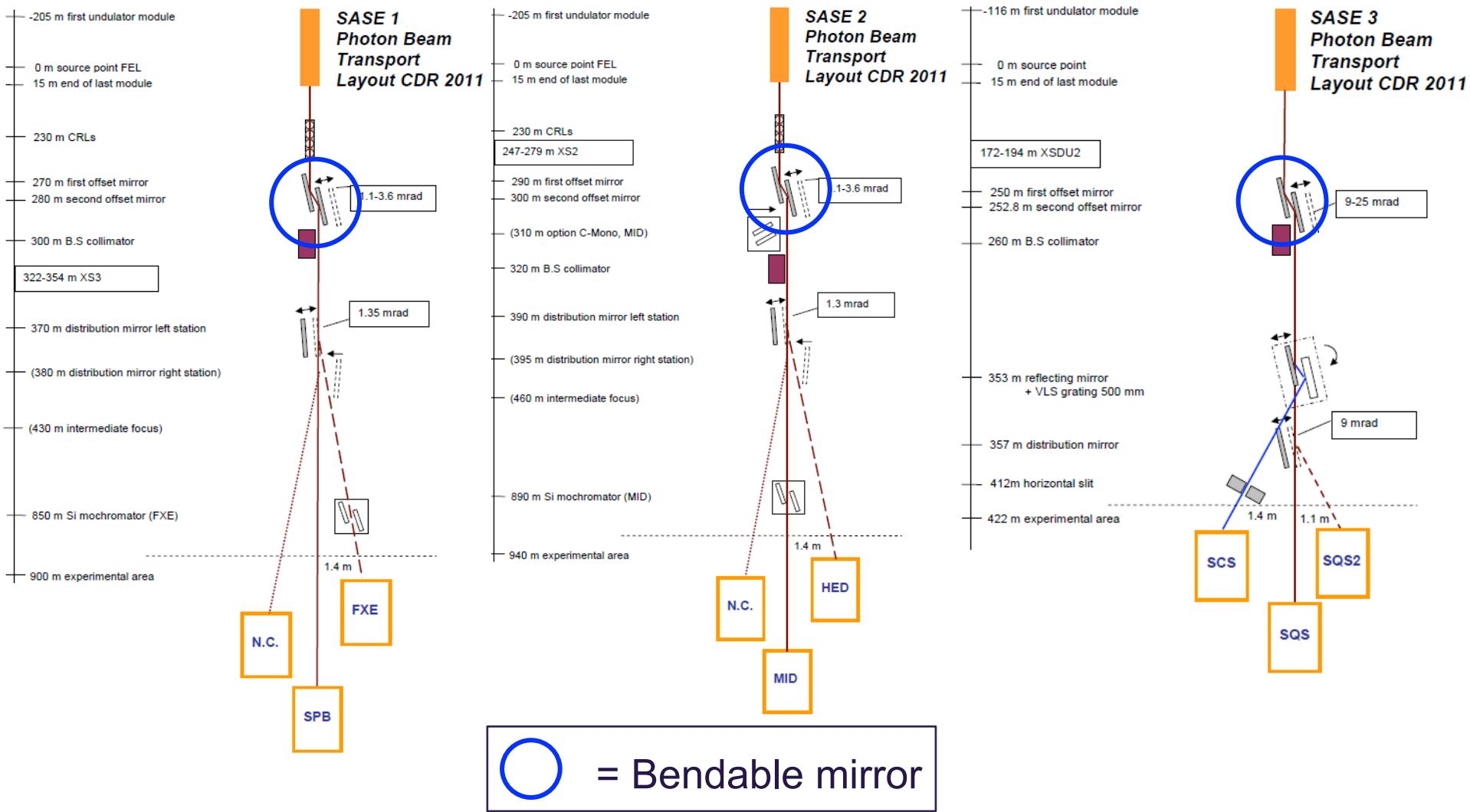
Dynamic thermal bump @ 10Hz

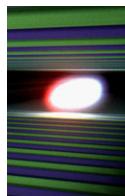


	Δz
Peak	18-33 nm
Average	15-29 nm



Bendable Mirrors in the Distribution System





Bendable Mirror design

Water-cooled copper blade in an indium-gallium liquid eutectic

applied voltage

X-ray beam

PZT

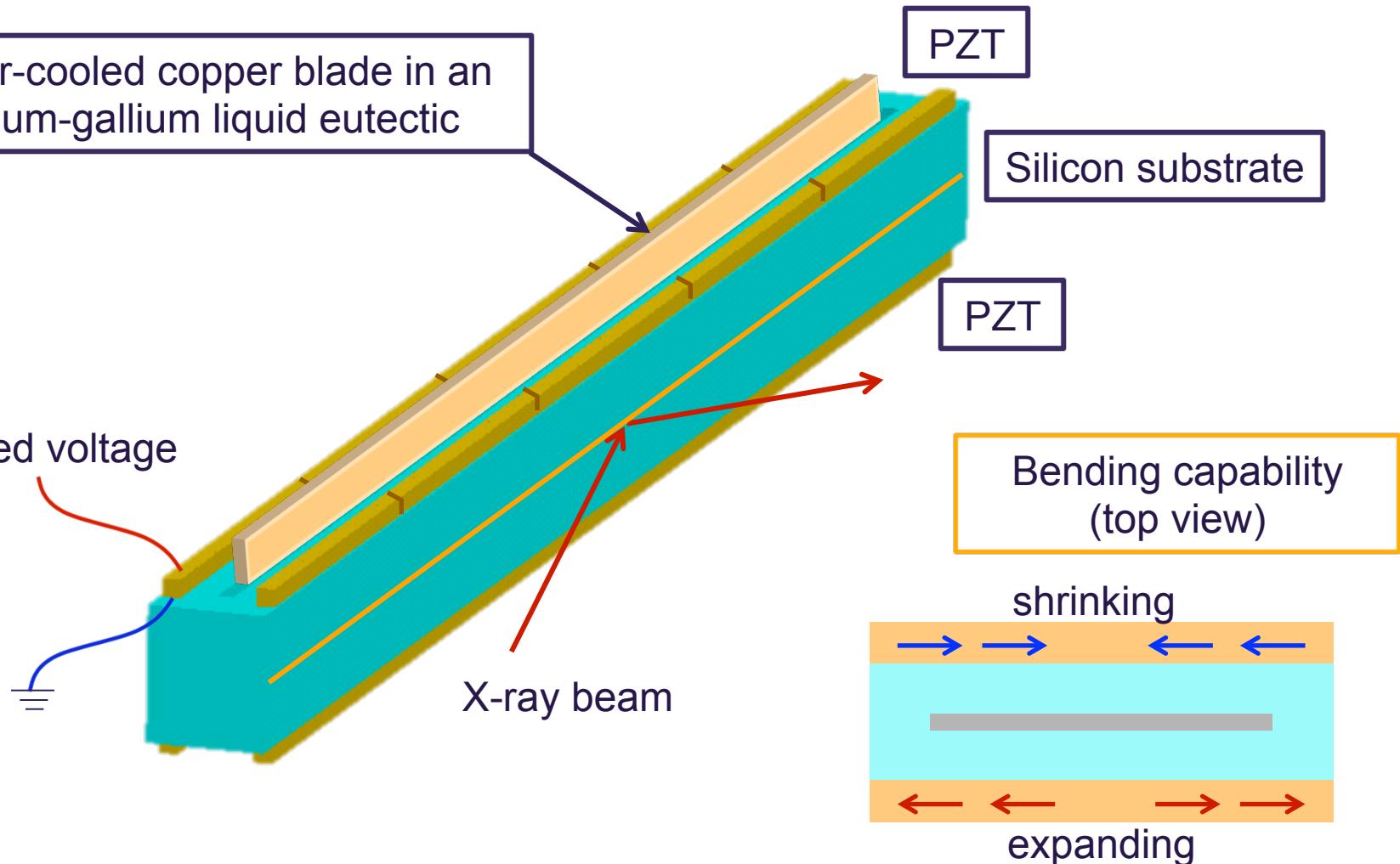
Silicon substrate

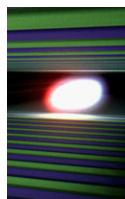
PZT

Bending capability
(top view)

shrinking

expanding

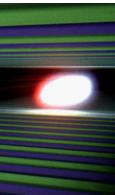




General Specification

	Mirror specifications	Prototype specifications
Substrate length	930 mm	950 mm
Optical surf (mer x sag)	800x20mm ²	750x20mm ²
Substrate Material	Single crystal silicon	Single crystal silicon
Surface coating	B ₄ C	none
Figure	Flat	Flat
Cooling system	InGa eutectic bath	Groove present but not used

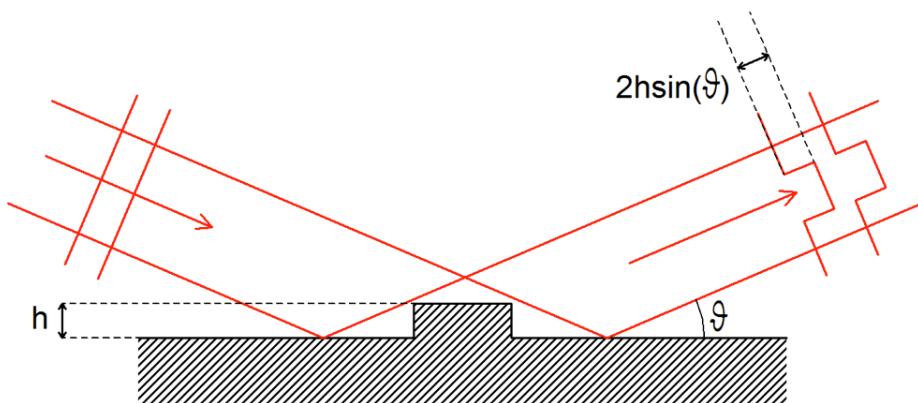
Height error (Peak to Valley) (4th order polynomial removed)	<2 nm	<20 nm
Slope error (root mean square)	<0.05 urad <0.5 urad sagittal	<1 urad <0.5 urad (3rd order removed) <5 urad sagittal
Roughness (@10x) rms	<0.3 nm	<0.3 nm
Radius of curvature	>600 km	>50 km >1 km sagittal
Bending capability	-50 km to flat to +50 km	-50 km to flat to +50 km



Wavefront distortion

Wavefront preservation depends on:

- Mirror length → diffraction on mirror edges
- Residual height errors



$$h_{rms} < \frac{1}{28} \frac{\lambda}{\sin \theta} \approx \frac{1}{28} \frac{\lambda}{\theta}$$

$$\varphi = \frac{2h \sin \theta}{\lambda}$$

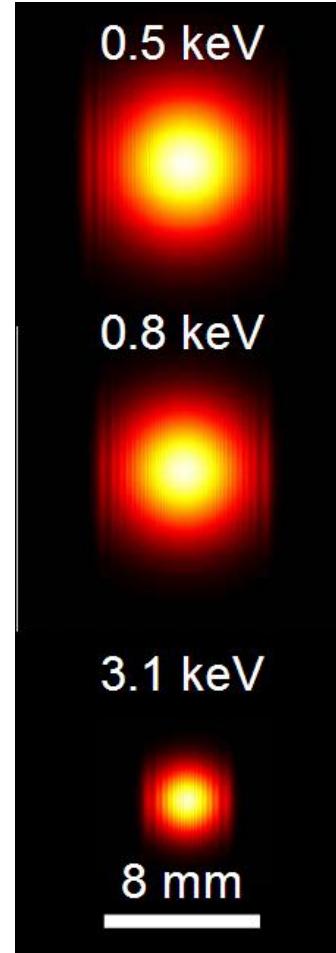
$$\varphi_{rms} \leq \frac{1}{14} \text{ Maréchal criteria}$$

φ : phase error

θ : “grazing” incidence angle

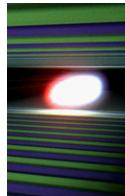
λ : beam wavelength

h : P-V error



Sinn, Samoylova, et al., “X-ray Optics and Beam Transport CDR”, April 2011 and F. Siewert et al., Optics Express **20**, 4525, (2012)

General Specifications



■ Why so long ?

To allow 4-sigma cutting and operation in different conditions/energies/footprint

To minimize thermal load over the surface

■ Why so “flat” ?

To reduce wavefront aberrations (fully coherent beam!)

■ Why bendable ?

To correct for the different beamlines length. To correct offset mirrors thermal load.

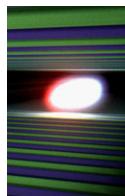
To correct low spatial frequency aberrations on the surface

■ Why InGa cooled ?

To allow mirror cooling without clamping (=bending)

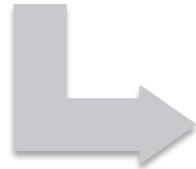
■ Why B4C coated ?

To protect the mirror from beam damage (eventual misalignment and misfocusing)

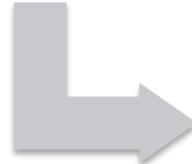


Prototype manufacturing

Substrate preparation +
Standard polishing



Ion Beam polishing
+ Internal Metrology

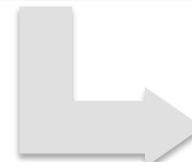


Metrology at BESSY
(HZB)

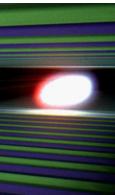
Today



Advanced polishing (EEM)
+ Internal Metrology

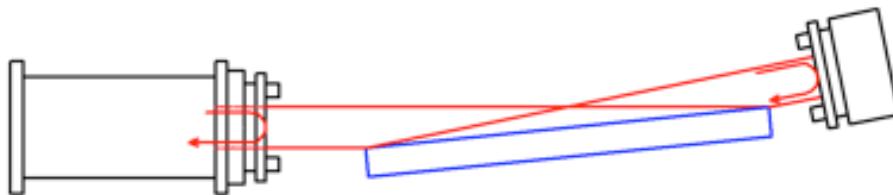


Final Metrology at
BESSY (HZB)



Internal Metrology (THALES-SESO)

Two different methods using Fizeau interferometry:



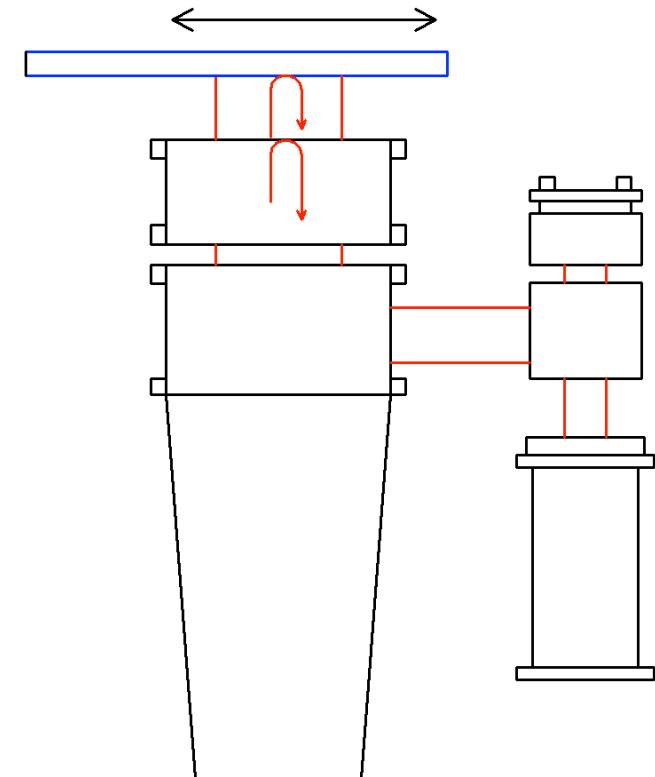
Grazing Incidence Setup

Pros:

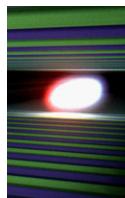
- Direct height profile measurement
- Full Map measurement
- High spatial resolution
- Fast (=seconds)

Cons:

- Limited by Reference Flat Calibration

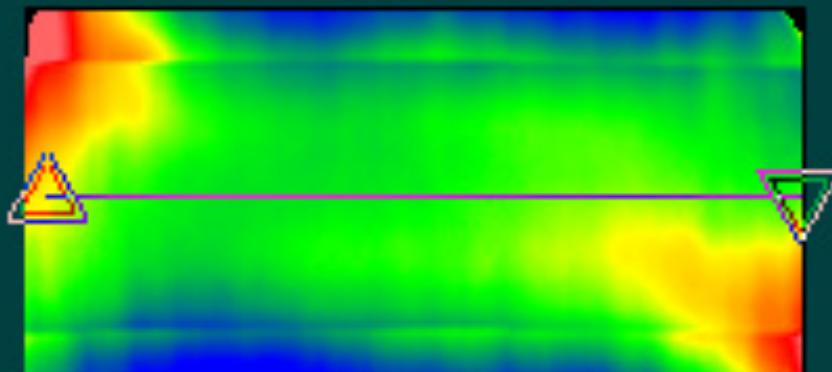


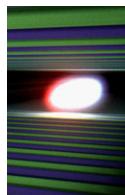
Normal Incidence/Stitching Setup



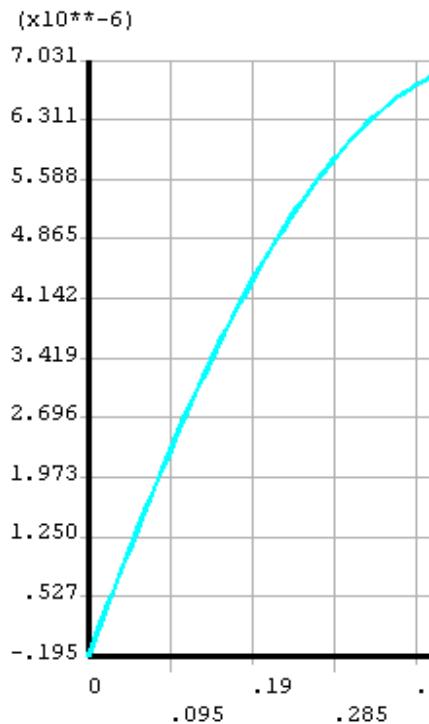
Full surface measurement (THALES-SESO)

Courtesy of Luca Peverini (THALES-SESO)

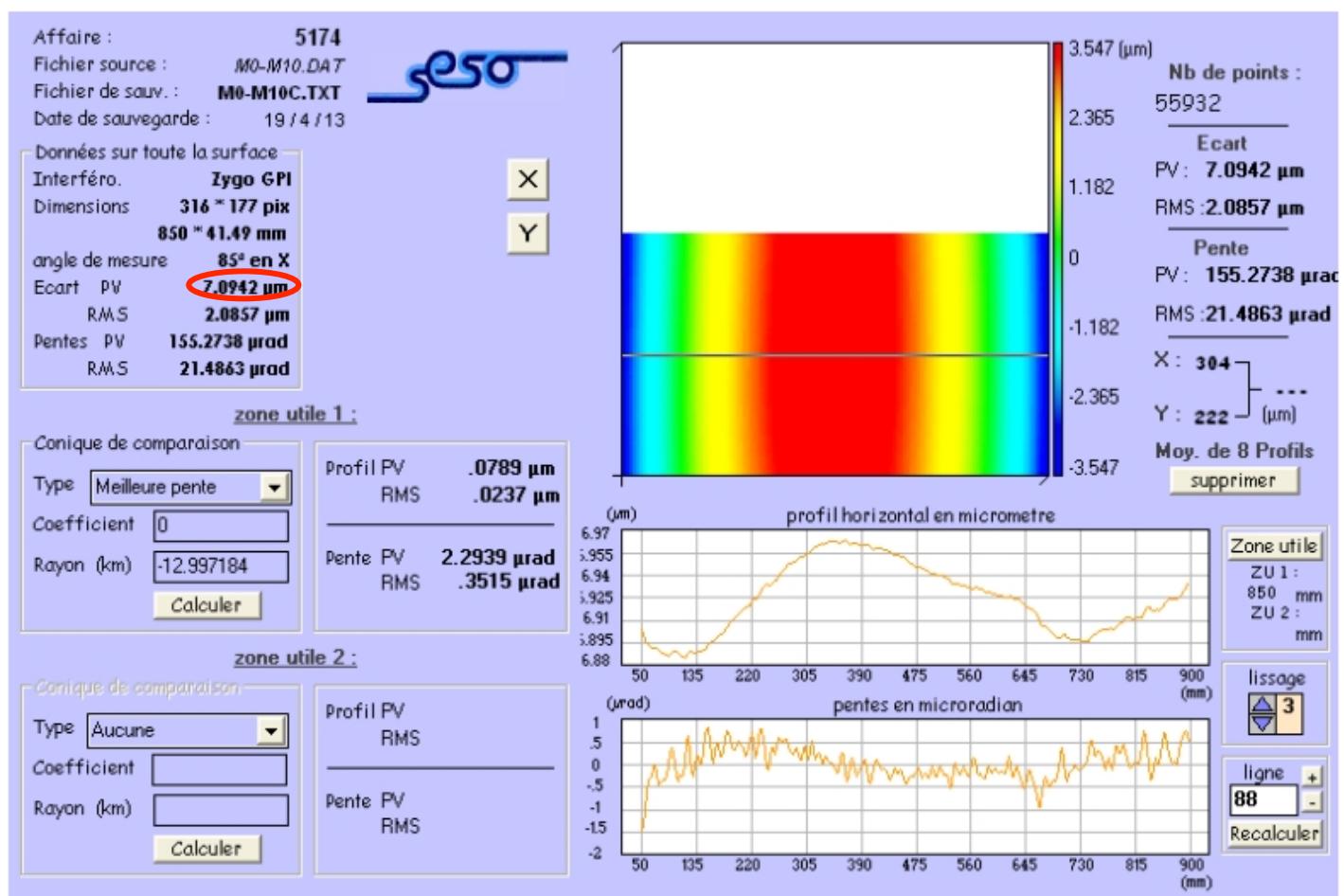


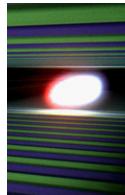


Simulations V.S. Measurements



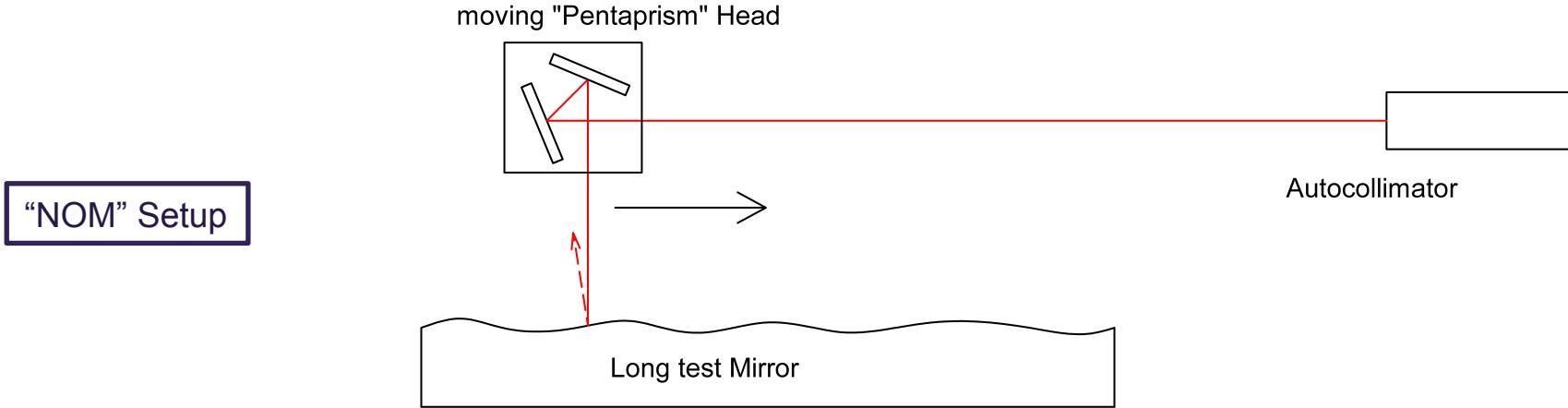
Simulations by Fan Yang





BESSY Metrology (Frank Siewert, HZG)

Deflectometric method:

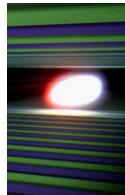


Pros:

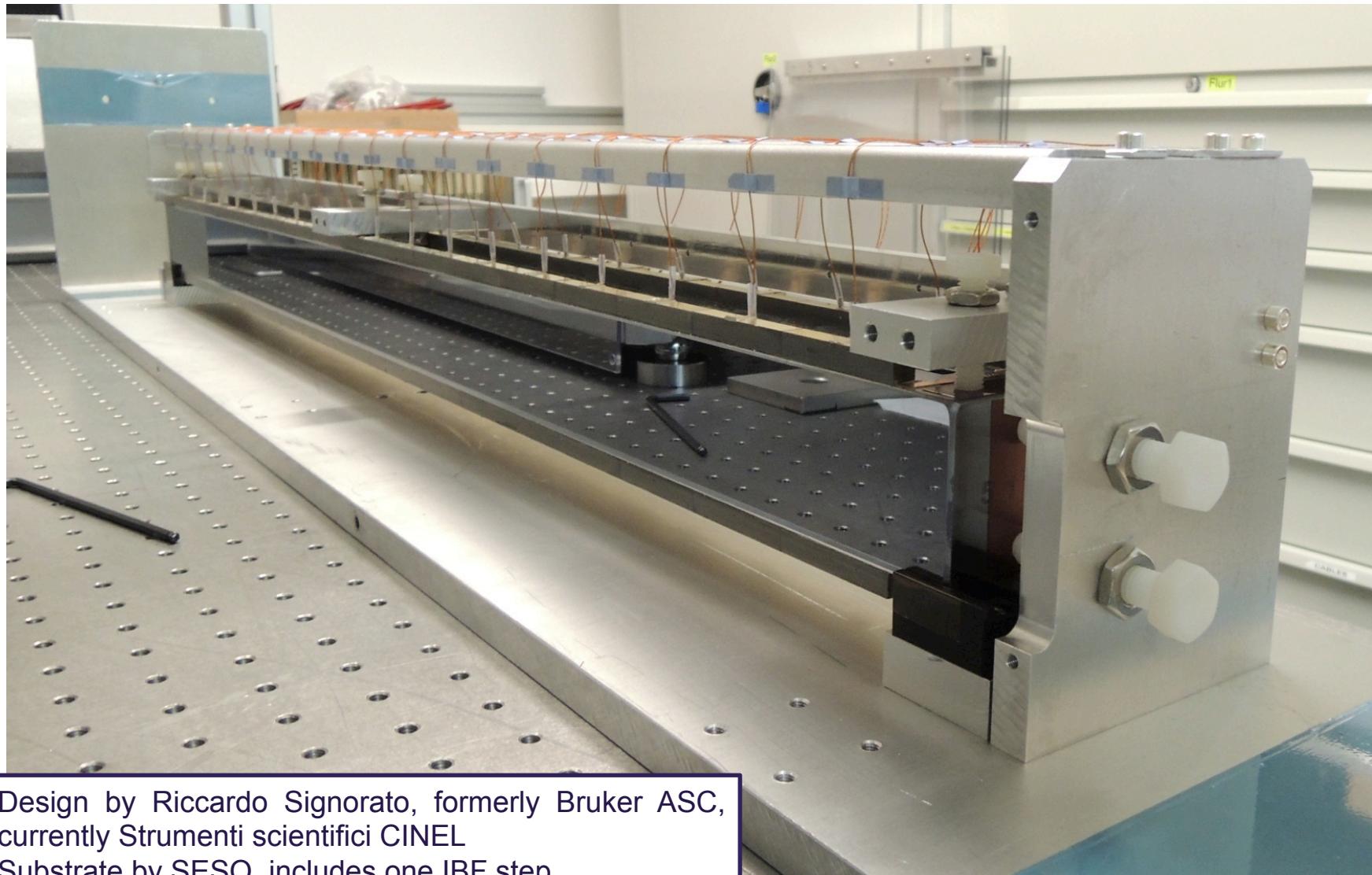
- No reference needed
- System already calibrated

Cons:

- Slope measurement (=indirect height profile measurement)
- “Slow” (=minutes)
- Limited to a profile in its basic implementation (but with BESSY-NOM, slope mapping is possible)



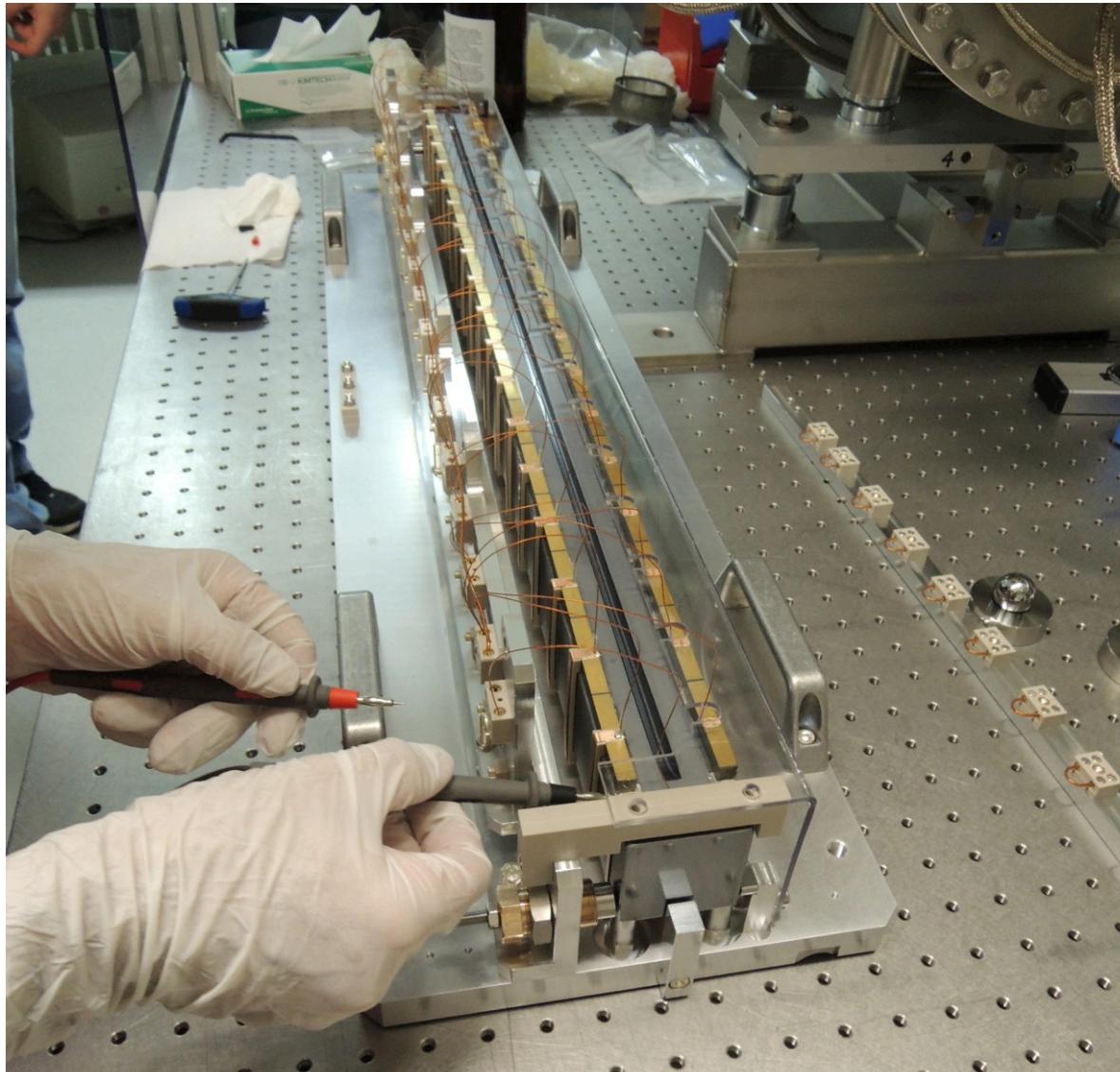
Prototype built by Bruker/CINEL/SESO



Design by Riccardo Signorato, formerly Bruker ASC,
currently Strumenti scientifici CINEL
Substrate by SESO, includes one IBF step

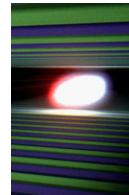
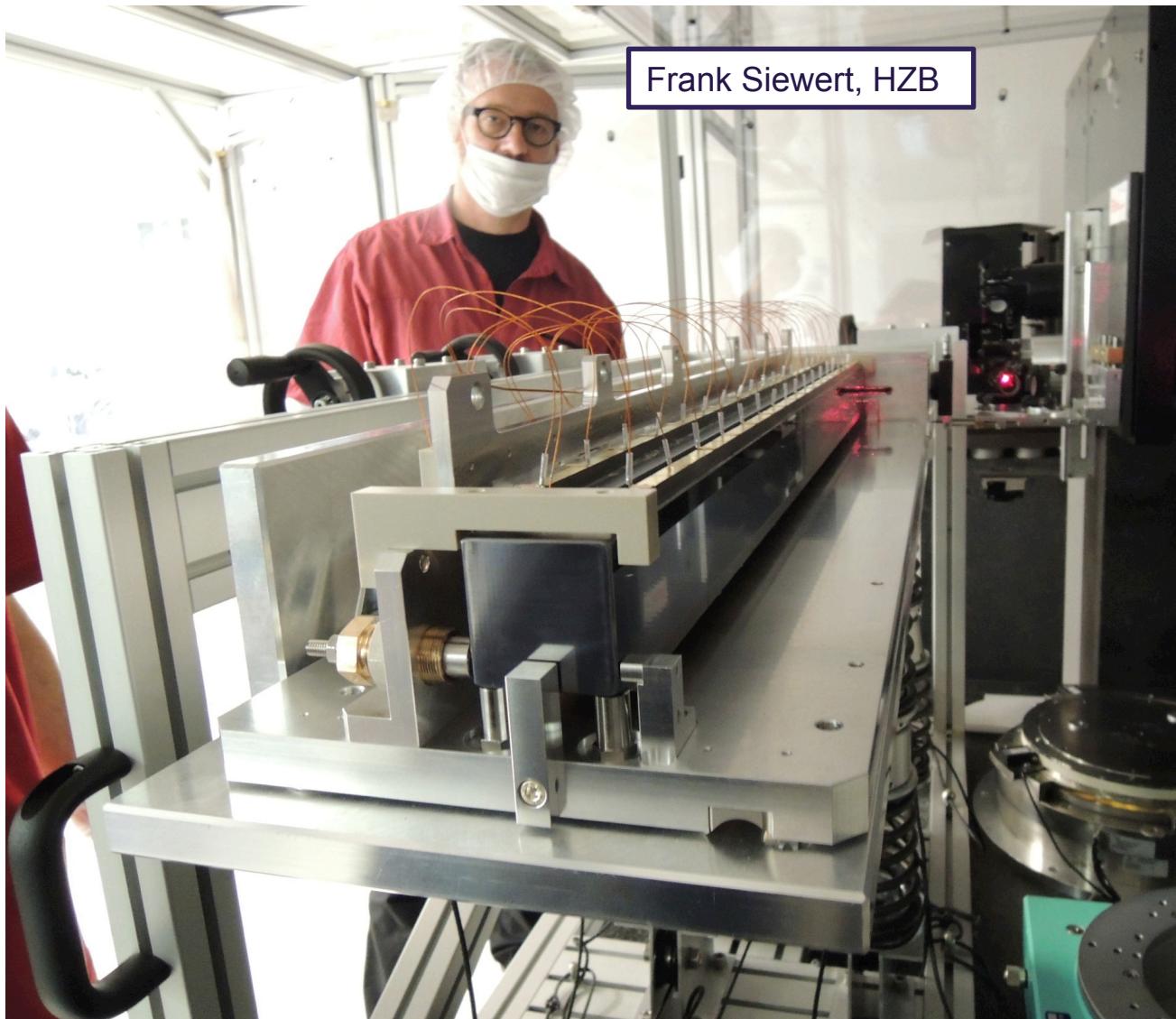
Prototype built by Bruker/CINEL/SESO

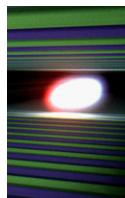
Hands of Riccardo Signorato



Measurements with NOM, BESSY

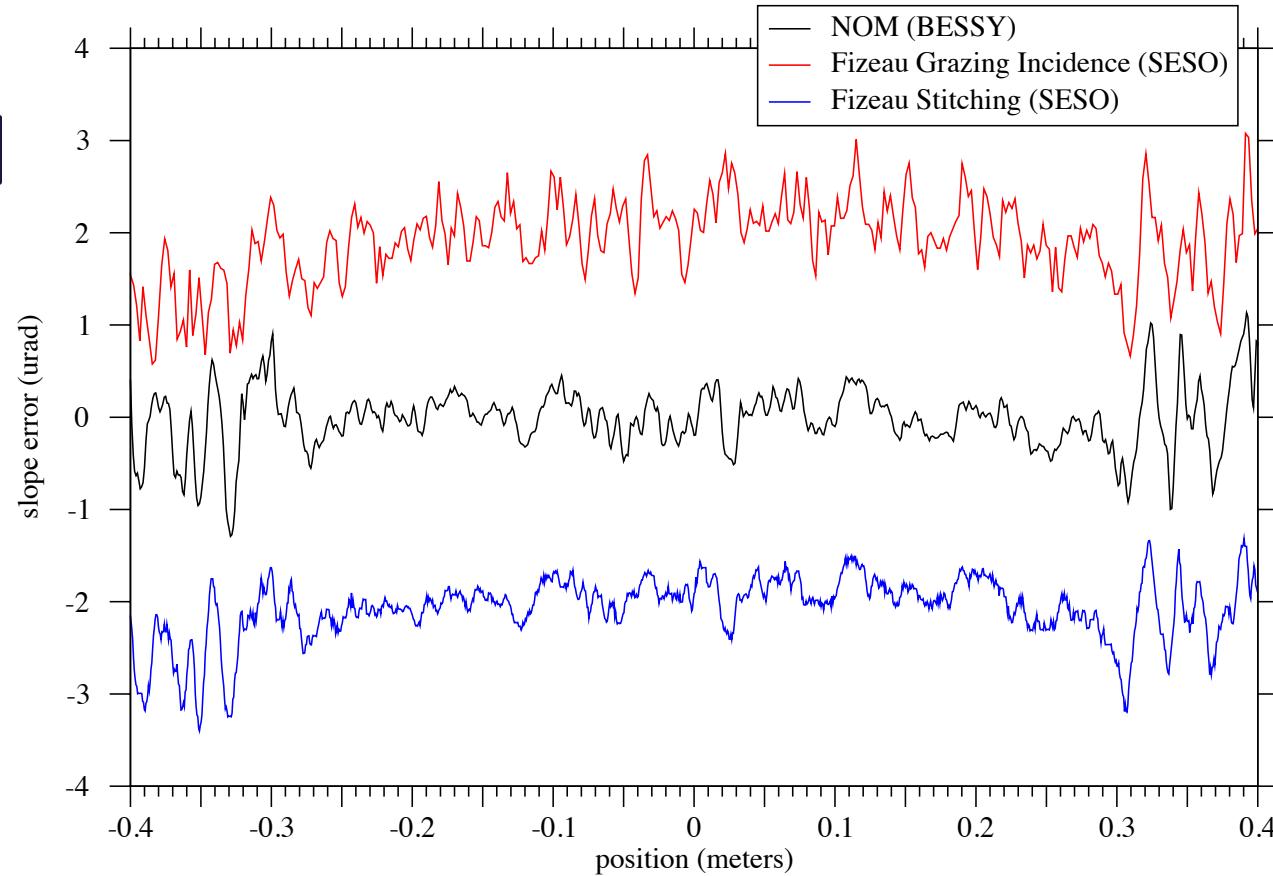
Frank Siewert, HZB





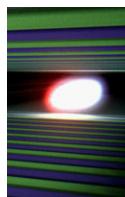
Metrology results

Residual slope error



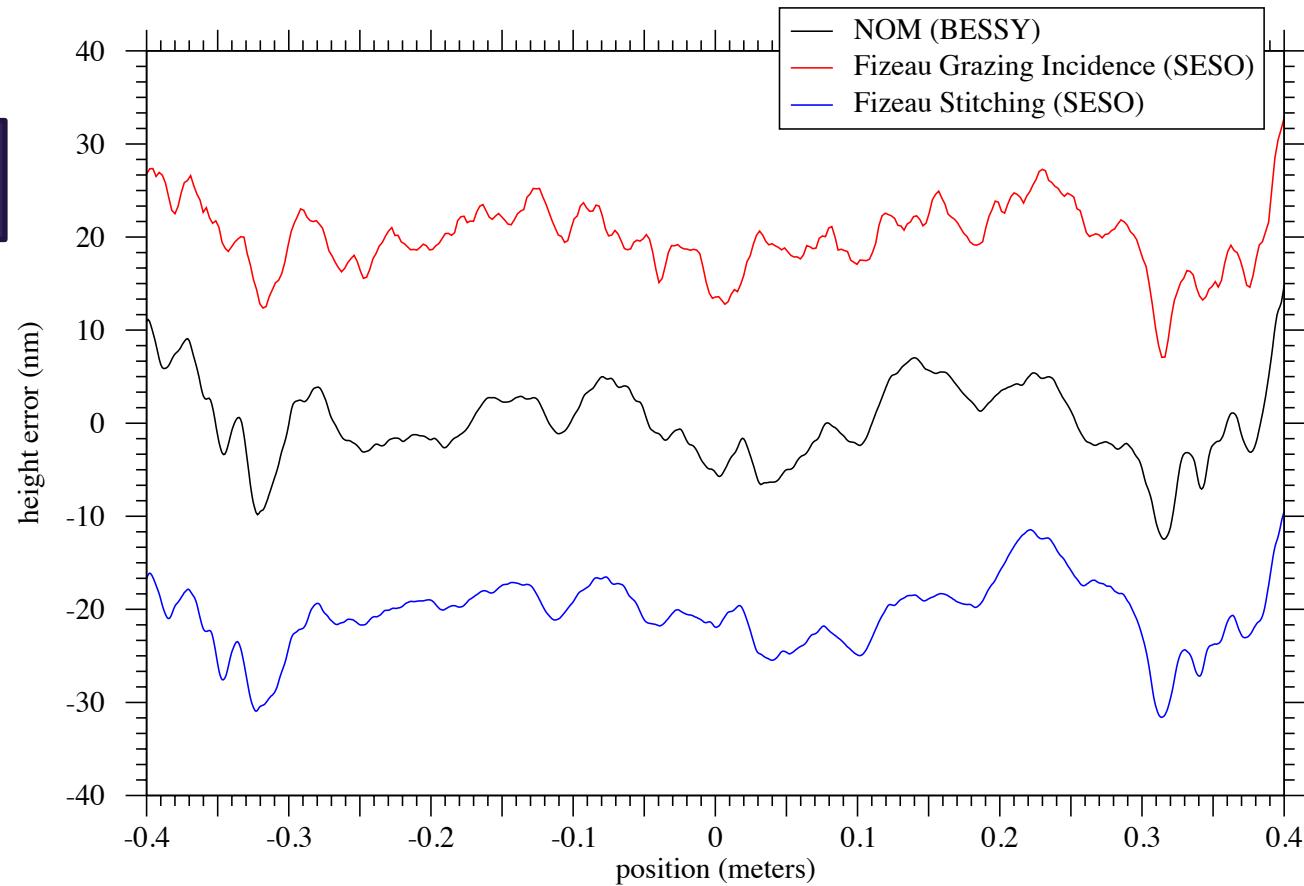
RMS residual slope error:

- NOM (BESSY): 0.317 urad
- SESO (Grazing Incidence): 0.345 urad
- SESO (Stitching): 0.319 urad



Metrology results

Height error profile
(3rd order correction)

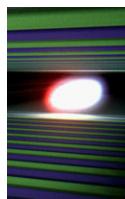


RMS height error (3rd order correction):

- NOM (BESSY): 3.8 nm
- SESO (Grazing Incidence): 3.2 nm
- SESO (Stitching): 3.6 nm

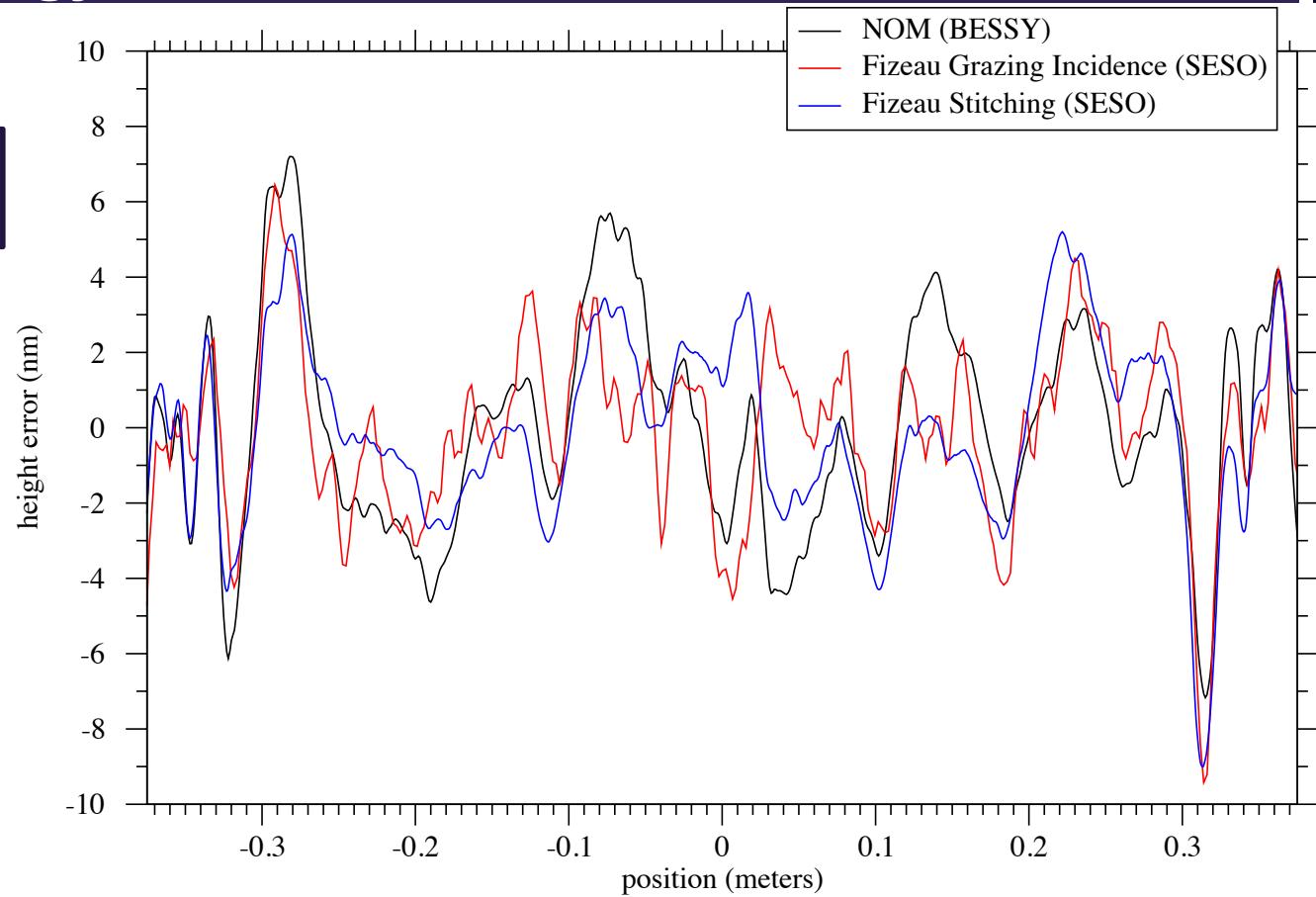
P-V height error (3rd order correction):

- NOM (BESSY): 18.7 nm
- SESO (Grazing Incidence): 18.0 nm
- SESO (Stitching): 18.8 nm



Metrology results

Height error profile
(6rd order correction)

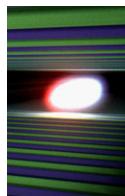


RMS height error (6rd order correction):

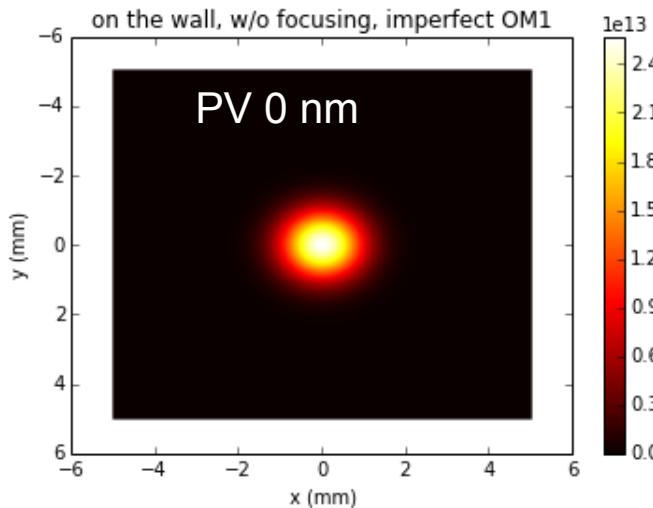
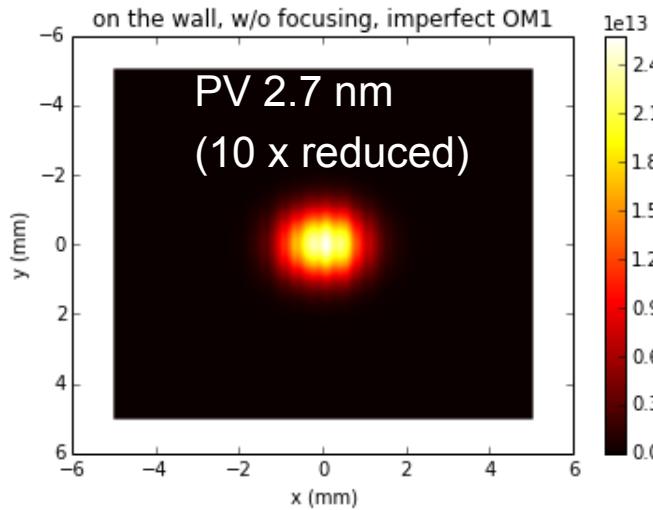
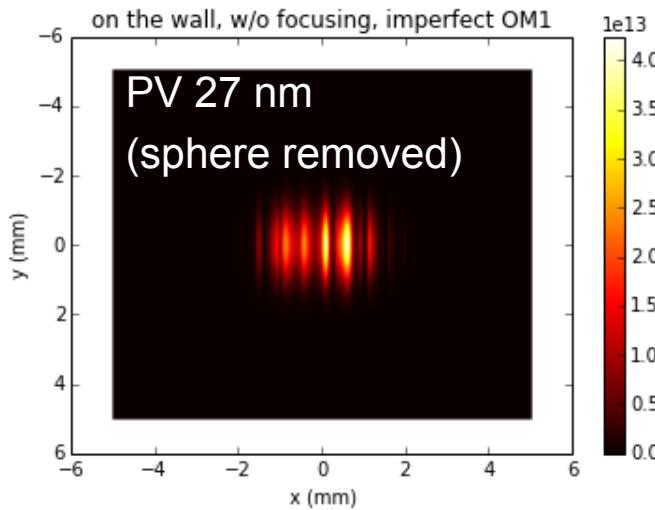
- NOM (BESSY): 2.8 nm
- SESO (Grazing Incidence): 2.3 nm
- SESO (Stitching): 2.4 nm

P-V height error (6rd order correction):

- NOM (BESSY): 14.4 nm
- SESO (Grazing Incidence): 15.9 nm
- SESO (Stitching): 14.2 nm



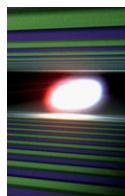
How would the prototype perform at E.XFEL?



SASE1 beamline,
simulated with:

12.4 KeV (= wl 0.1 nm),
distance 625 m,
grazing angle 2 millirad,
e-bunch charge 0.1 nC

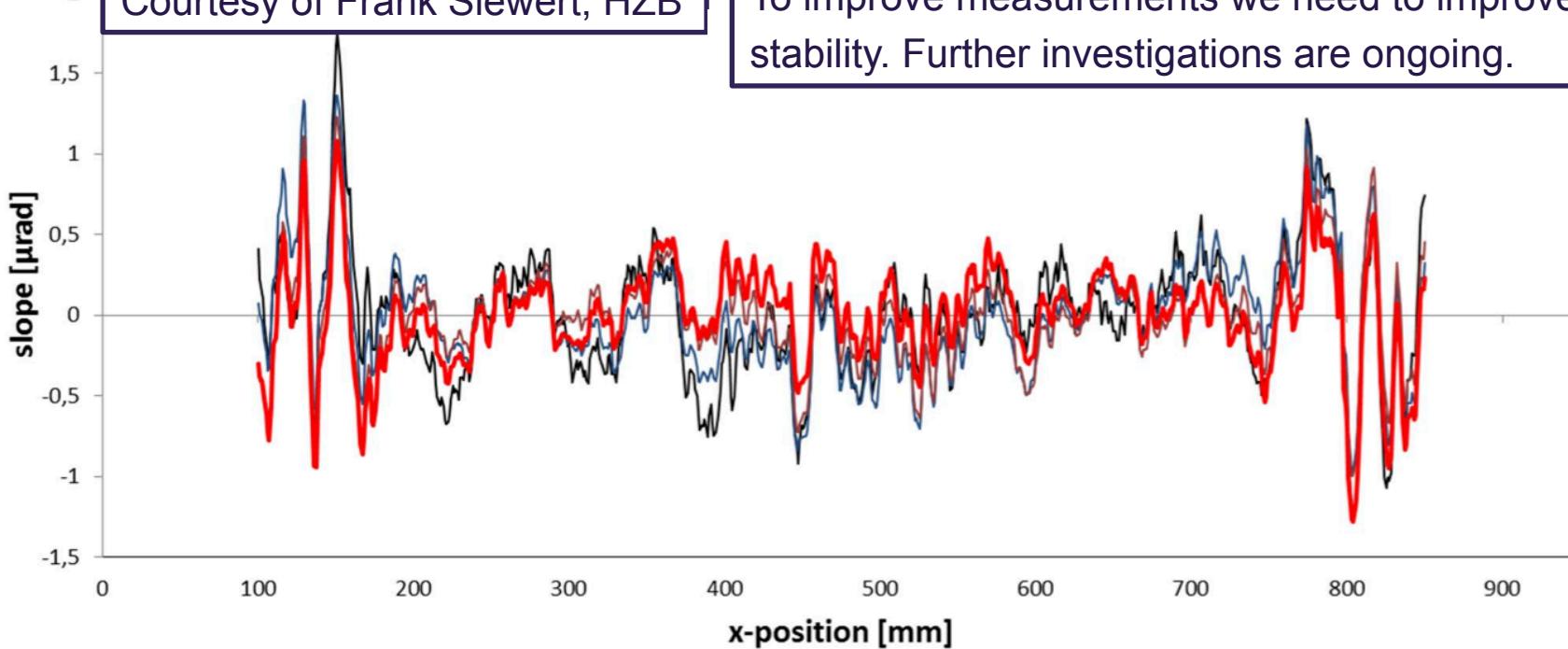
Calculations
by
Liubov
Samoylova,
Maurizio
Vannoni



Stability issues

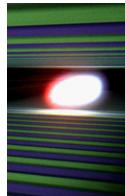
Courtesy of Frank Siewert, HZB

To improve measurements we need to improve the stability. Further investigations are ongoing.



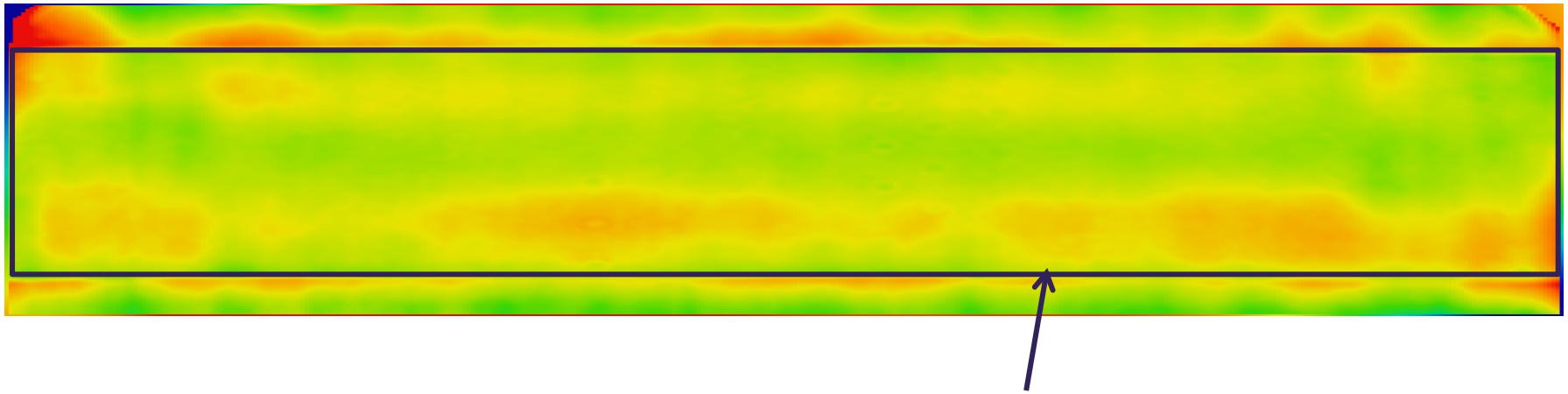
Residual slope: 0.31 μrad rms on 750 mm length

Radius of curvature: -650 km (convex)

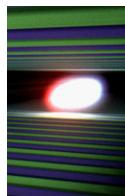


Full surface measurements (THALES-SESO)

Height map



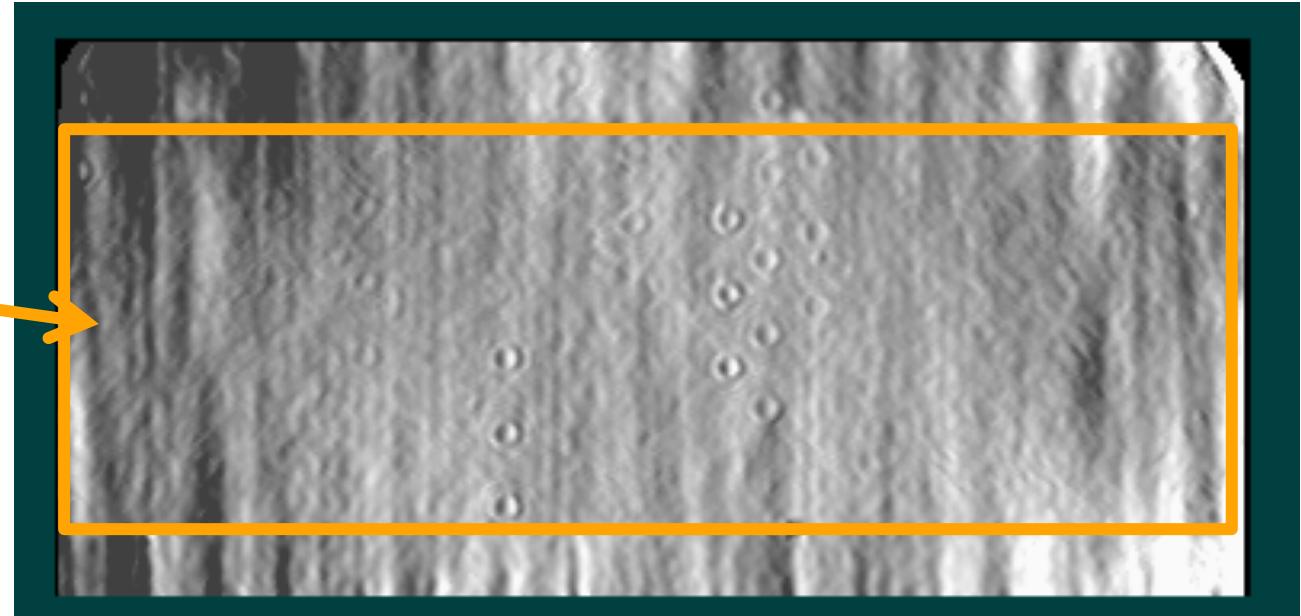
Ion Beam polished area



Full surface measurements (THALES-SESO)

Slope map

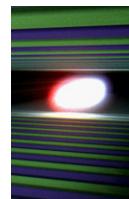
Ion Beam
polished
area



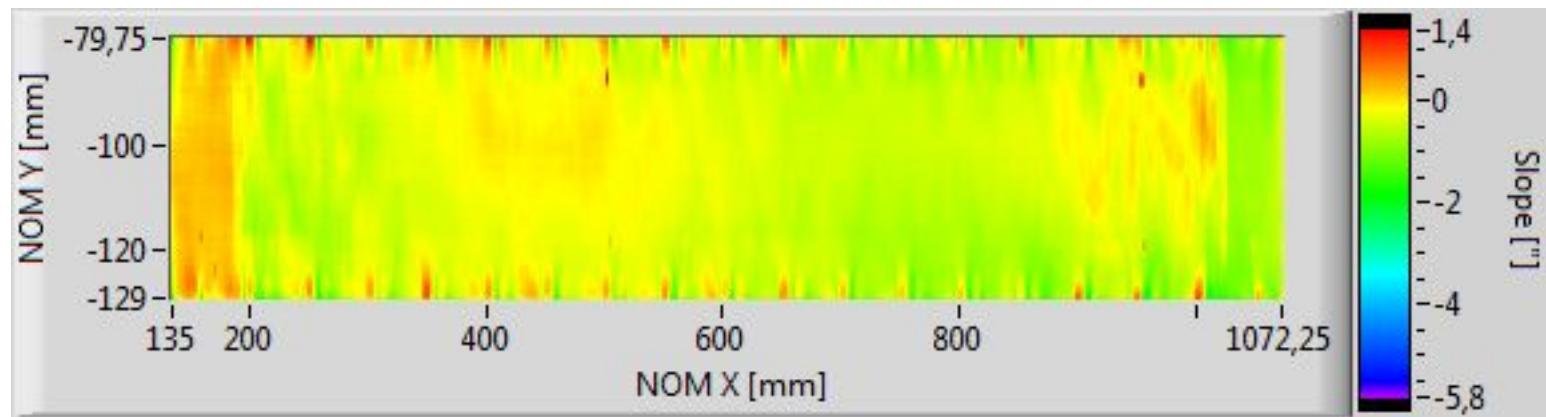
piezo

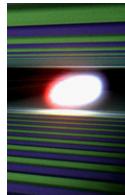


Full surface measurement (HZB)



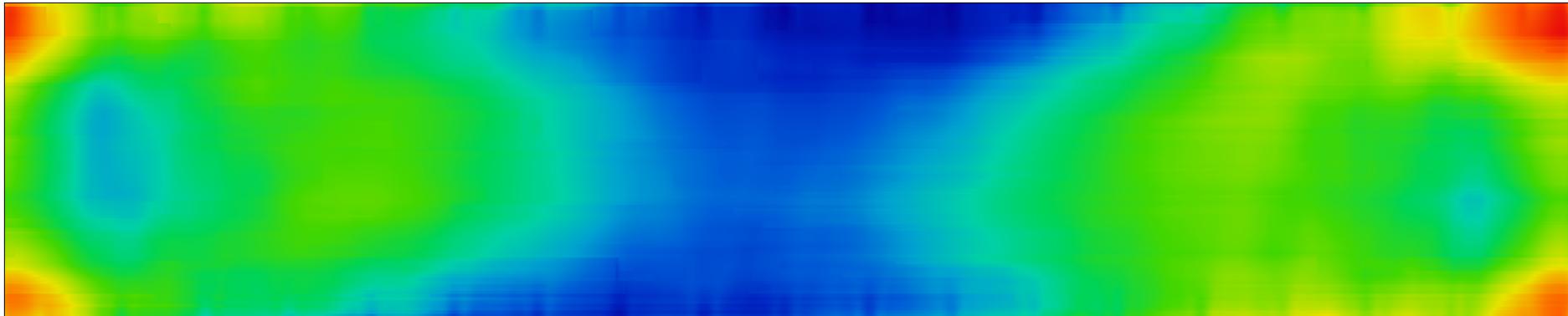
Slope map



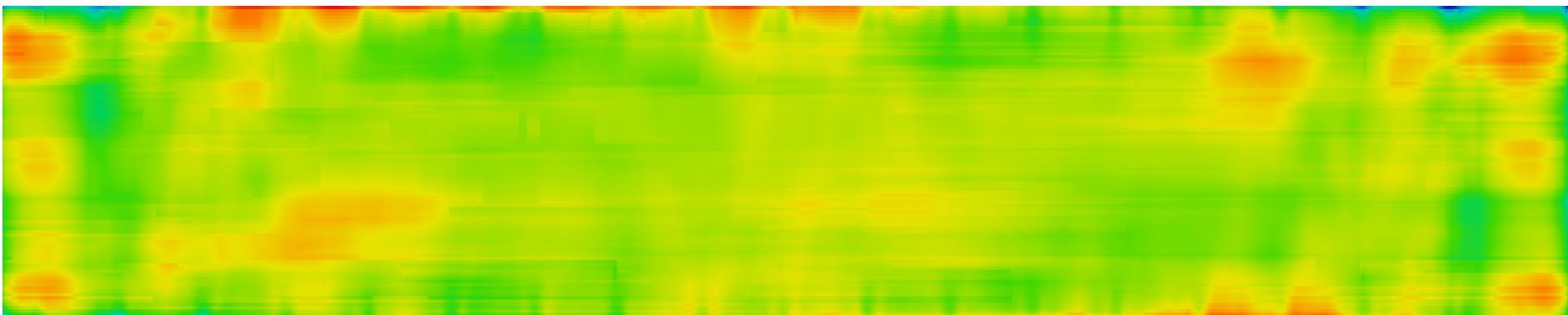


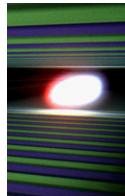
Full surface measurement (HZB)

Height map – face up



Height map – face up – polynomial subtracted





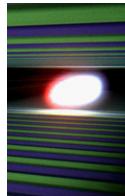
Conclusions

■ Present state:

- The prototype is ok with specifications
- The metrology is stretched to the limit but still reliable.
- Combining height and slope measurements we retrieve additional information

■ Further details to investigate

- Piezo characterization, EEM polishing (JTEC), B4C coating, InGa cooling...



Acknowledgments

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- Frank Siewert and 
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